

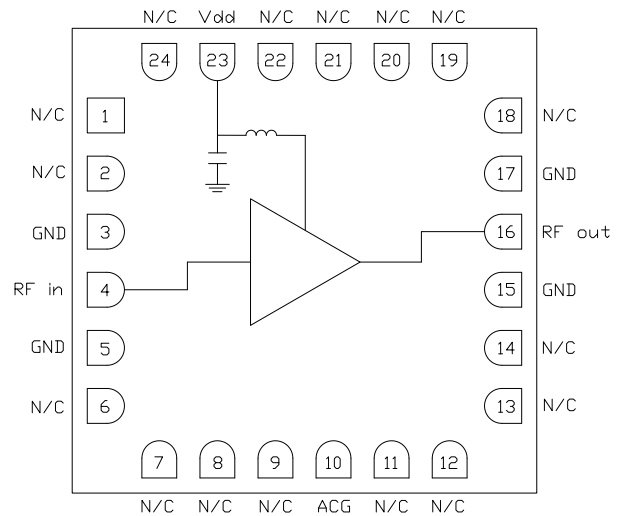
### Features

- ▶ Wide bandwidth
- ▶ High linearity
- ▶ Single positive supply voltage
- ▶ On chip bias choke
- ▶ Pb-free RoHs compliant 4x4 mm SMT package

### Description

The CMD317C4 is a wideband GaAs MMIC driver amplifier housed in a leadless 4x4 mm surface mount package. The CMD317C4 is ideally suited for military, space and communications systems where small size and high linearity are needed. At 12 GHz the device delivers 16 dB of gain with a corresponding output 1 dB compression point of +23 dBm and an output IP3 of 35 dBm. The CMD317C4 is a 50 ohm matched design which eliminates the need for RF port matching and includes an on chip bias choke.

### Functional Block Diagram



### Electrical Performance - $V_{dd} = 8.0 \text{ V}$ , $T_A = 25 \text{ }^\circ\text{C}$ , $F = 12 \text{ GHz}$

| Parameter          | Min    | Typ | Max | Units |
|--------------------|--------|-----|-----|-------|
| Frequency Range    | 1 - 24 |     |     | GHz   |
| Gain               |        | 16  |     | dB    |
| Input Return Loss  |        | 18  |     | dB    |
| Output Return Loss |        | 16  |     | dB    |
| Output P1dB        |        | 23  |     | dBm   |
| Output IP3         |        | 35  |     | dBm   |
| Supply Current     |        | 225 |     | mA    |



# CMD317C4

## 1-24 GHz Distributed Driver Amplifier

### Specifications

#### Absolute Maximum Ratings

| Parameter                            | Rating        |
|--------------------------------------|---------------|
| Drain Voltage, V <sub>dd</sub>       | 9 V           |
| RF Input Power                       | +20 dBm       |
| Channel Temperature, T <sub>ch</sub> | 150 °C        |
| Power Dissipation, P <sub>diss</sub> | 2.62 W        |
| Thermal Resistance, $\Theta_{JC}$    | 24.8 °C/W     |
| Operating Temperature                | -40 to 85 °C  |
| Storage Temperature                  | -55 to 150 °C |

Exceeding any one or combination of the maximum ratings may cause permanent damage to the device.

#### Recommended Operating Conditions

| Parameter       | Min | Typ | Max | Units |
|-----------------|-----|-----|-----|-------|
| V <sub>dd</sub> | 5.0 | 8.0 | 8.5 | V     |
| I <sub>dd</sub> |     | 225 |     | mA    |

Electrical performance is measured at specific test conditions. Electrical specifications are not guaranteed over all recommended operating conditions.

#### Drain Current vs. Drain Voltage

| V <sub>dd</sub> (V) | I <sub>dd</sub> (mA) |
|---------------------|----------------------|
| 5.0                 | 130                  |
| 8.0                 | 225                  |

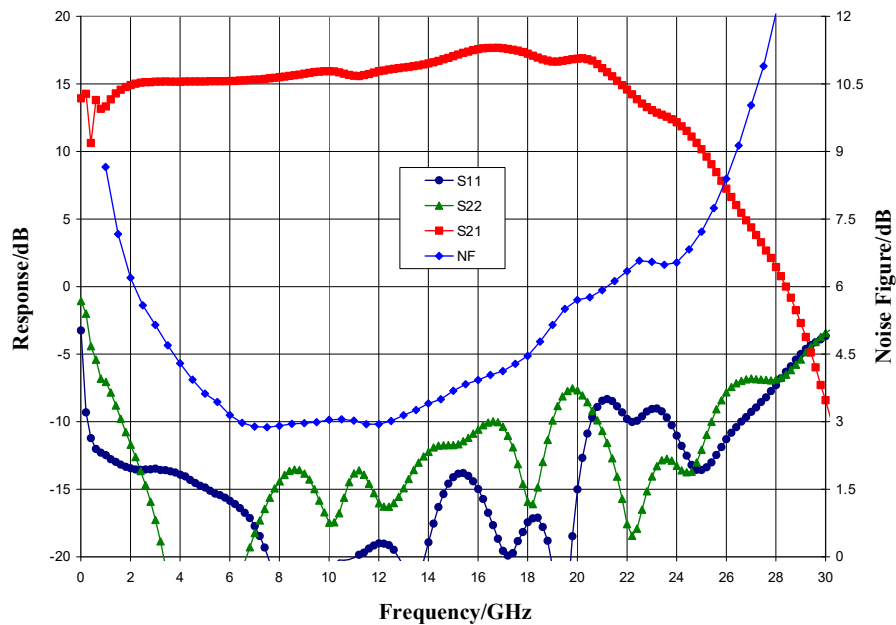
#### Electrical Specifications, V<sub>dd</sub> = 8.0 V, T<sub>A</sub> = 25 °C

| Parameter                            | Min    | Typ   | Max | Min     | Typ   | Max | Min     | Typ   | Max | Units |
|--------------------------------------|--------|-------|-----|---------|-------|-----|---------|-------|-----|-------|
| Frequency Range                      | 1 - 10 |       |     | 10 - 20 |       |     | 20 - 24 |       |     | GHz   |
| Gain                                 | 10.5   | 15    |     | 12.5    | 17    |     | 9.5     | 15    |     | dB    |
| Noise Figure                         |        | 4     |     |         | 3.5   |     |         | 6.5   |     | dB    |
| Input Return Loss                    |        | 15    |     |         | 15    |     |         | 10    |     | dB    |
| Output Return Loss                   |        | 13    |     |         | 10    |     |         | 12    |     | dB    |
| Output P <sub>1dB</sub>              | 19.5   | 23    |     | 18      | 22    |     | 15      | 19    |     | dBm   |
| Output IP <sub>3</sub>               |        | 36    |     |         | 34    |     |         | 27    |     | dBm   |
| Supply Current                       | 170    | 225   | 280 | 170     | 225   | 280 | 170     | 225   | 280 | mA    |
| Gain Temperature Coefficient         |        | 0.012 |     |         | 0.014 |     |         | 0.023 |     | dB/°C |
| Noise Figure Temperature Coefficient |        | 0.009 |     |         | 0.012 |     |         | 0.016 |     | dB/°C |

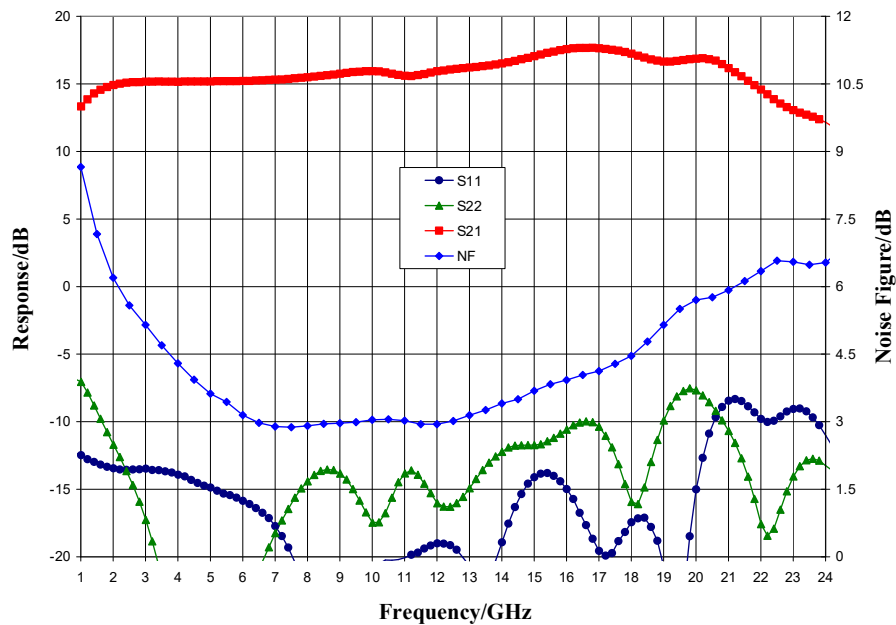
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### Typical Performance

**Broadband Performance,  $V_{dd} = 8.0$  V,  $T_A = 25$  °C**



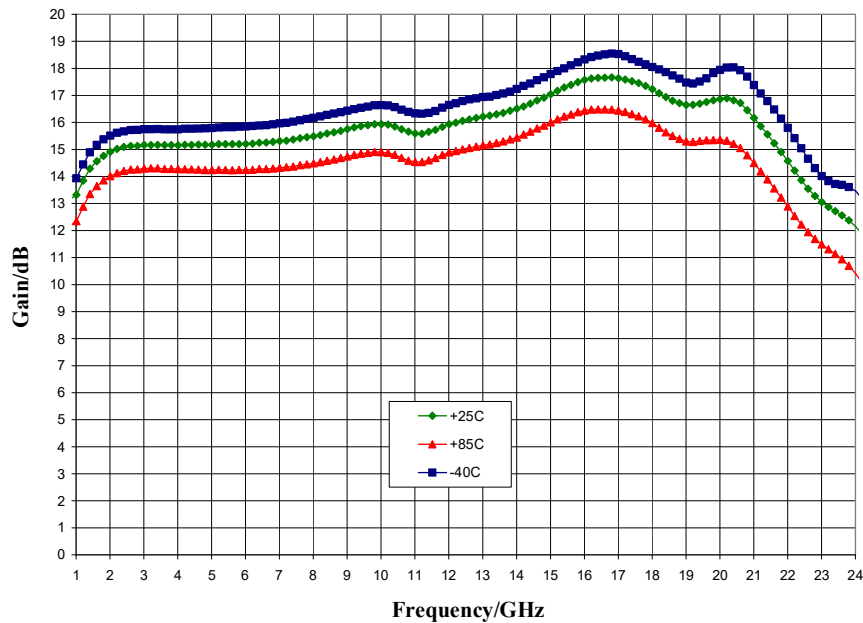
**Narrow-band Performance,  $V_{dd} = 8.0$  V,  $T_A = 25$  °C**



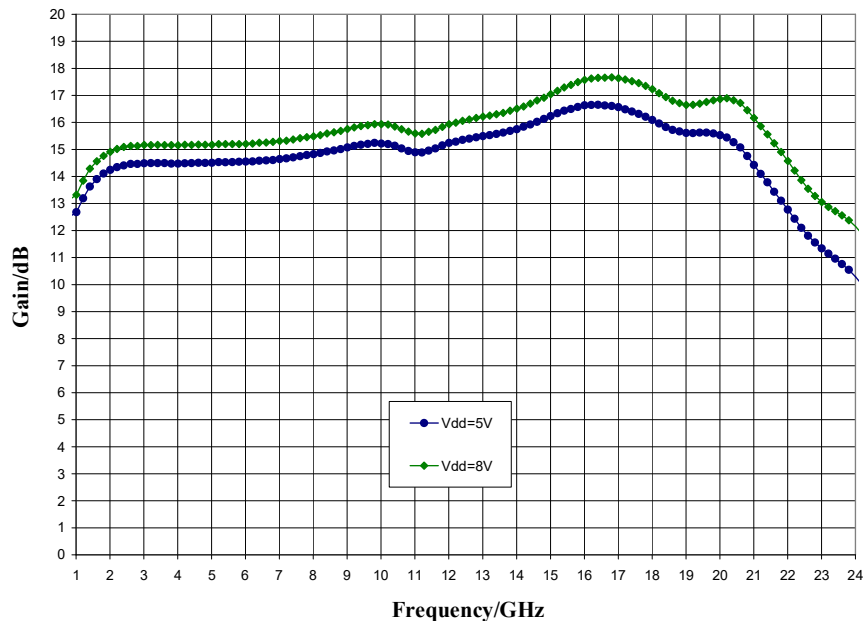
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### Typical Performance

Gain vs. Temperature,  $V_{dd} = 8.0 \text{ V}$

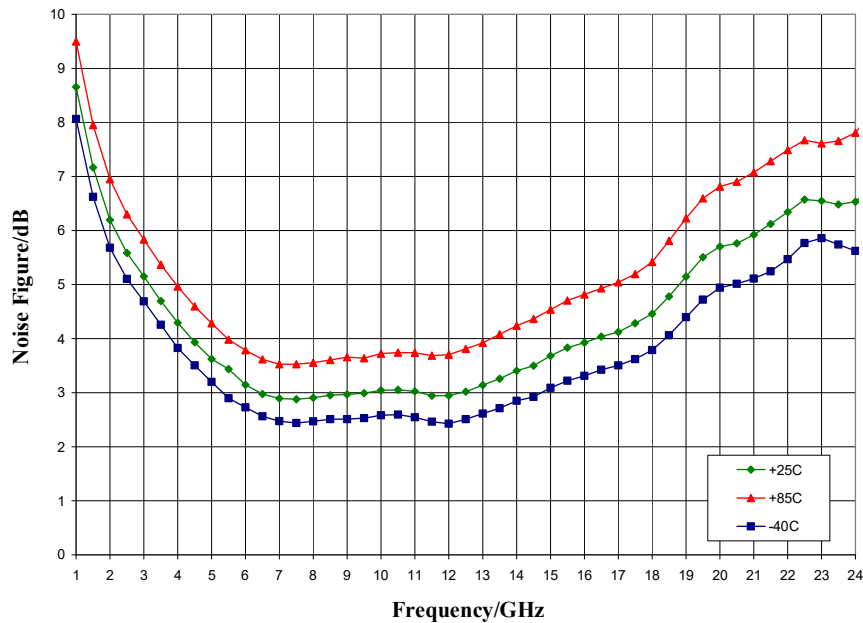


Gain vs.  $V_{dd}$ ,  $T_A = 25 \text{ }^\circ\text{C}$

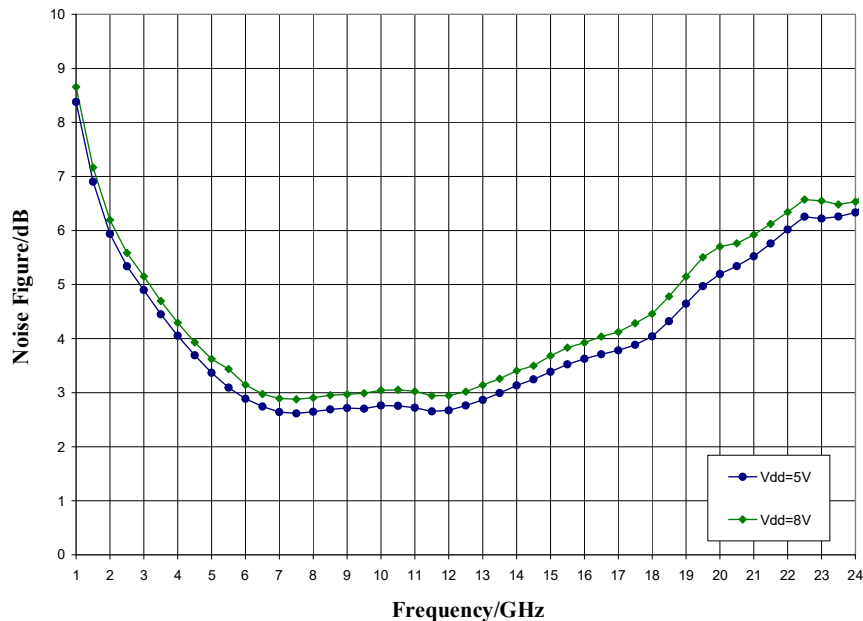


### Typical Performance

Noise Figure vs. Temperature,  $V_{dd} = 8.0\text{ V}$

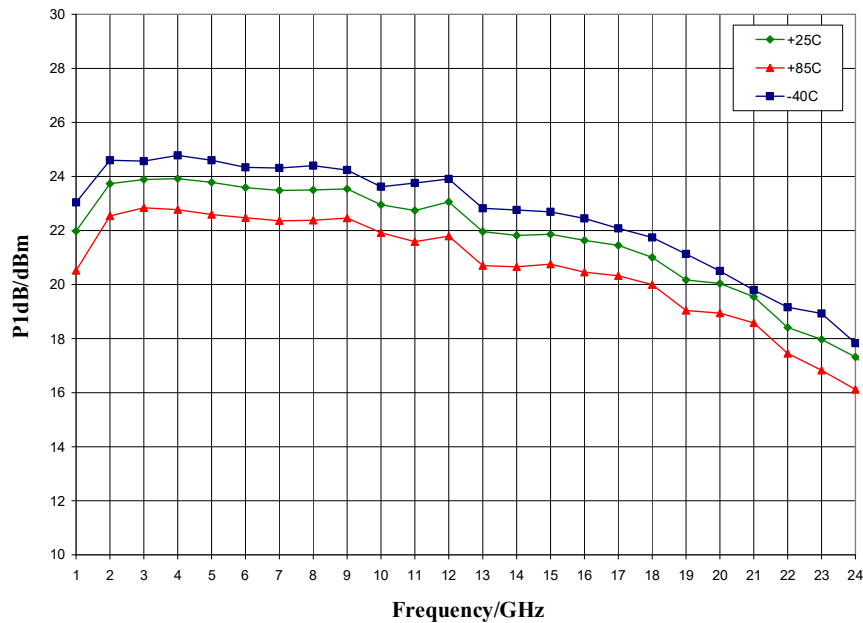


Noise Figure vs.  $V_{dd}$ ,  $T_A = 25\text{ }^\circ\text{C}$

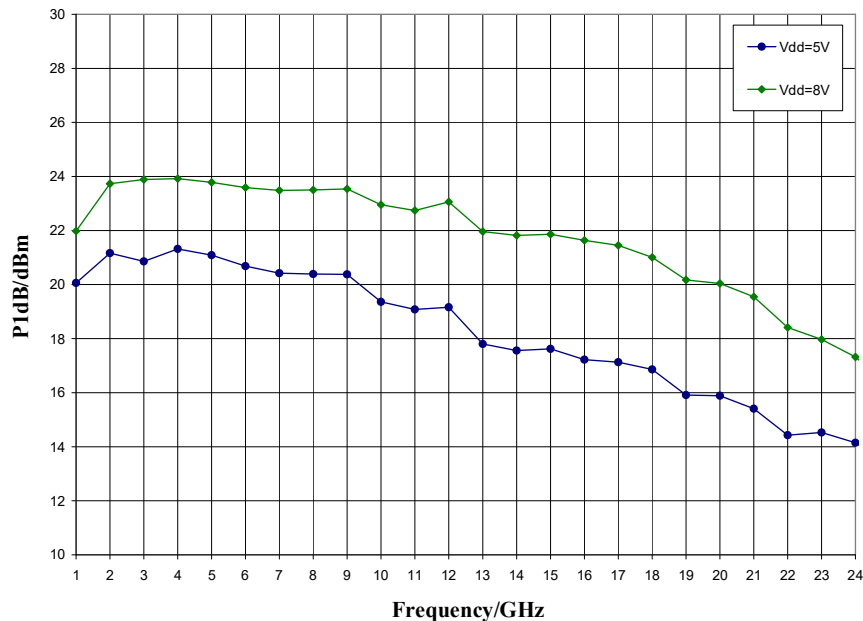


### Typical Performance

**P1dB vs. Temperature,  $V_{dd} = 8.0\text{ V}$**

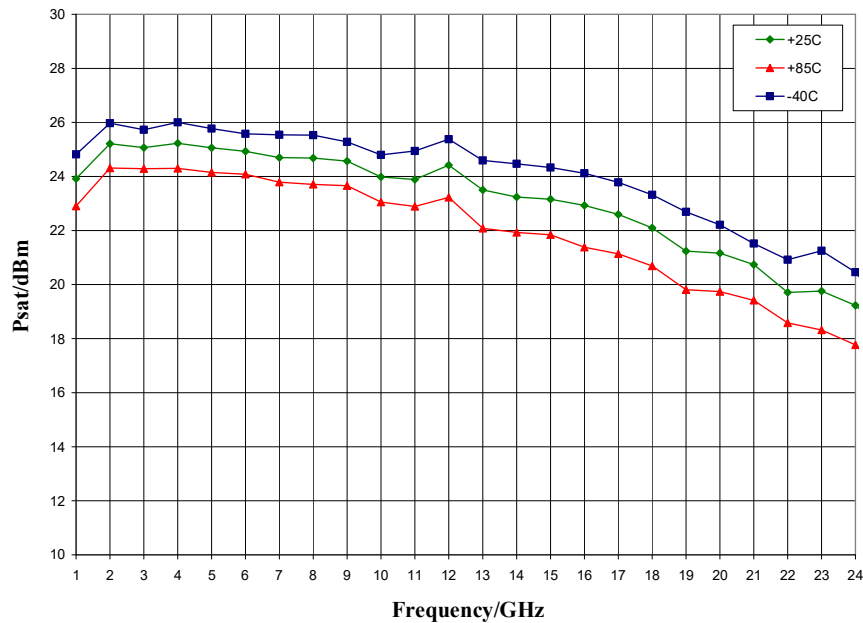


**P1dB vs.  $V_{dd}$ ,  $T_A = 25\text{ }^\circ\text{C}$**

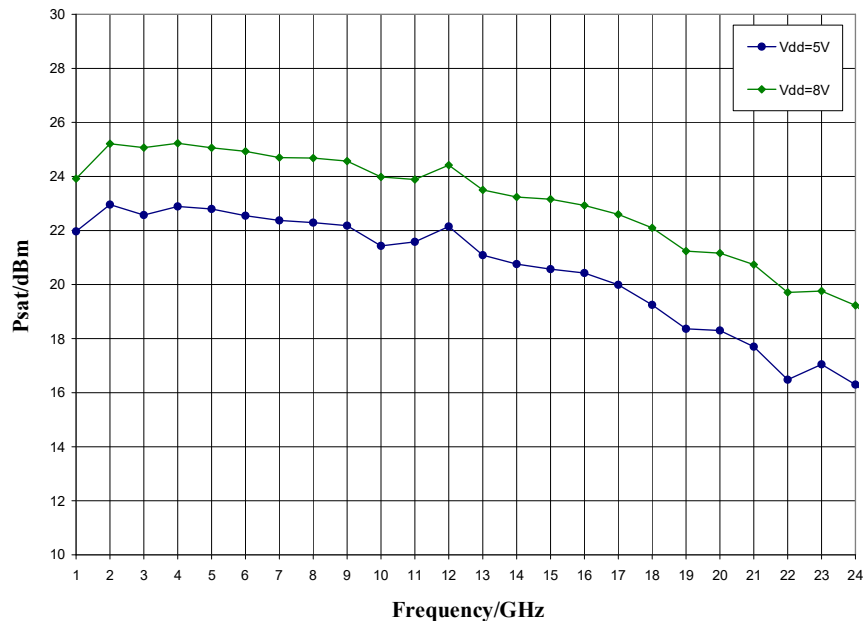


### Typical Performance

**Psat vs. Temperature,  $V_{dd} = 8.0\text{ V}$**



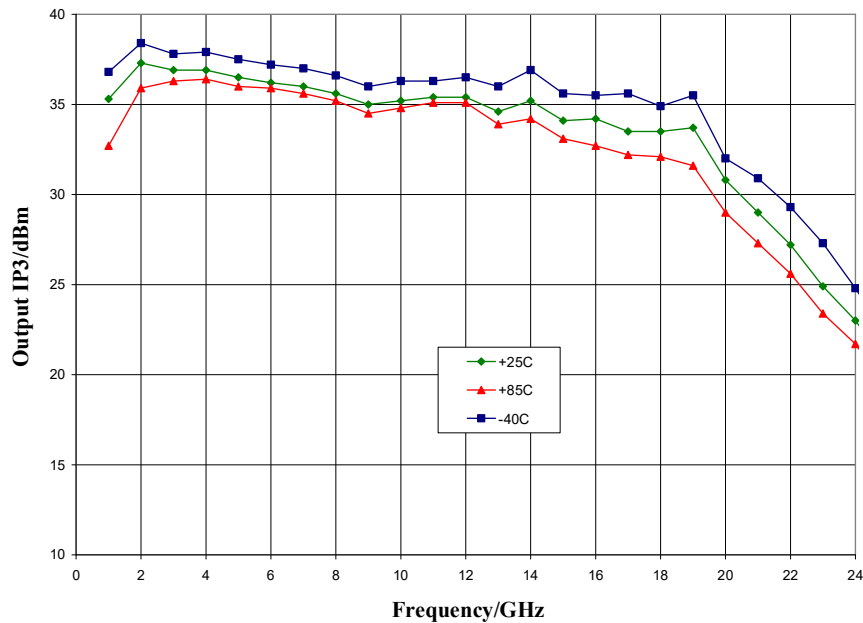
**Psat vs.  $V_{dd}$ ,  $T_A = 25\text{ }^\circ\text{C}$**



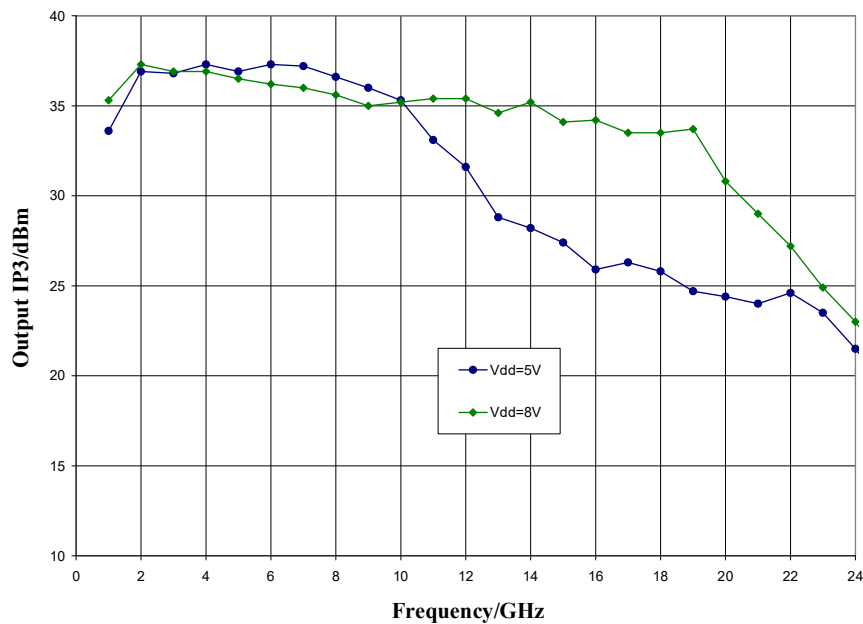
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### Typical Performance

Output IP3 vs. Temperature,  $V_{dd} = 8.0\text{ V}$

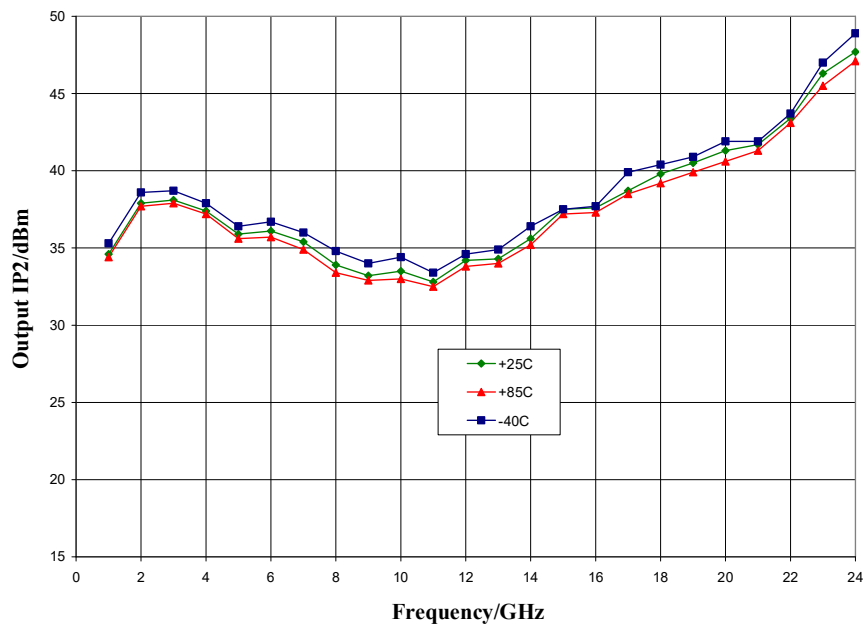


Output IP3 vs.  $V_{dd}$ ,  $T_A = 25\text{ }^\circ\text{C}$

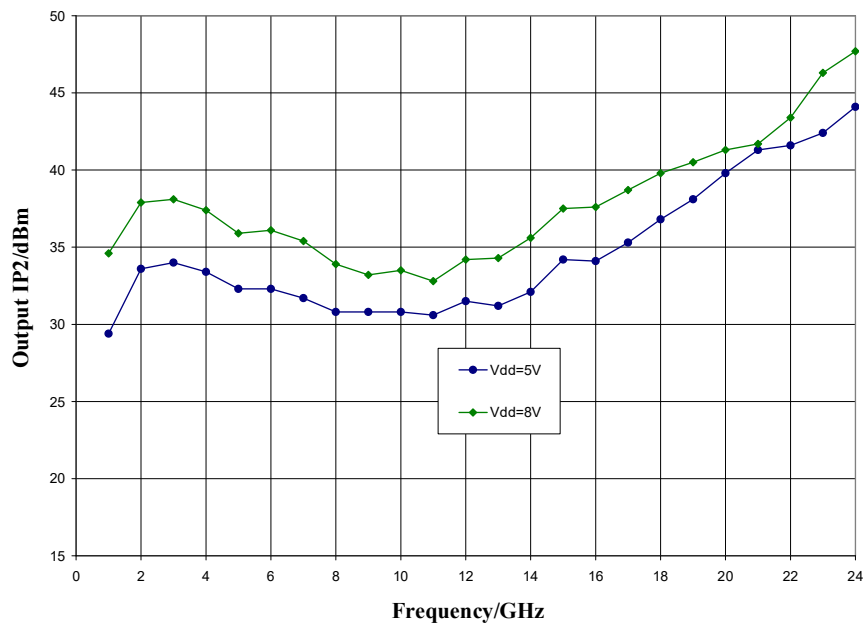


### Typical Performance

Output IP2 vs. Temperature,  $V_{dd} = 8.0\text{ V}$

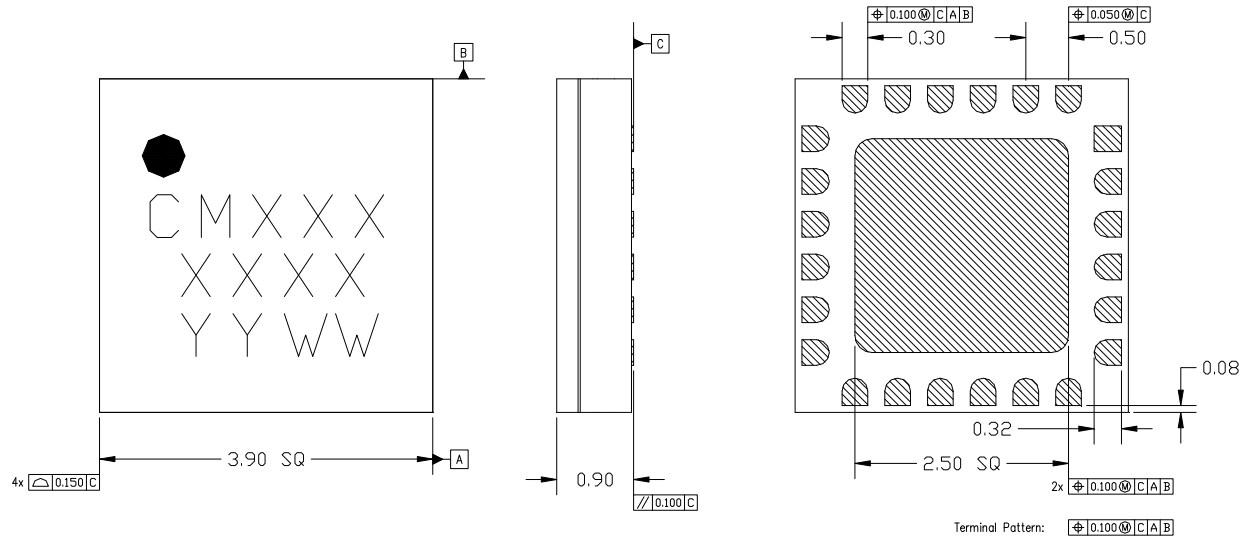


Output IP2 vs.  $V_{dd}$ ,  $T_A = 25\text{ }^\circ\text{C}$



### Mechanical Information

#### Package Information and Dimensions



#### NOTES:

1. ALL DIMENSIONS SHOWN IN mm.
2. MATERIAL: BLACK ALUMINA
3. LEAD FINISH:
  - 3.1. Ni: 8.89um MAX, 1.27um MIN
  - 3.2. Pd: 0.17um MAX, 0.07um MIN
  - 3.3. Au: 0.254um MAX, 0.03um MIN
4. MARKING
  - 4.1. LINE 1: PART NUMBER
    - 4.1.1. EXAMPLE: CMD191C4 SHALL BE MARKED AS CM191
  - 4.2. LINE 2: LOT NUMBER
  - 4.3. LINE 3: DATE CODE - LAST 2 DIGITS OF THE YEAR OF MANUFACTURE FOLLOWED BY A 2 DIGIT WEEK CODE
5. ALTERNATE PIN #1 IDENTIFIER IS A SINGLE SQUARE PAD
6. ALTERNATE DIE PADDLE MAY HAVE CHAMFERED CORNERS

#### Recommended PCB Land Pattern

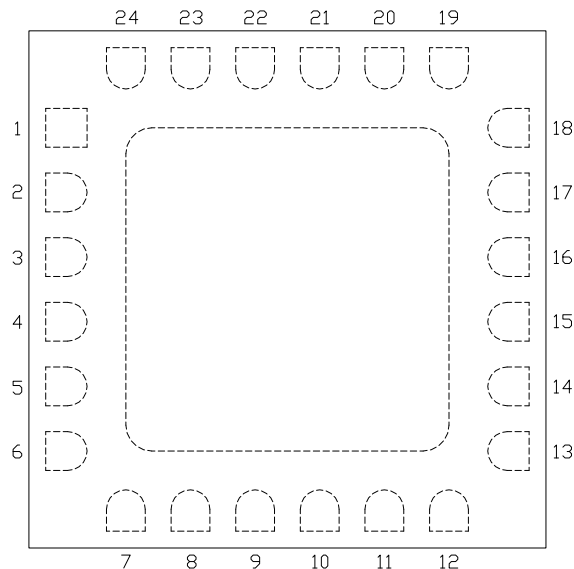
Custom MMIC recommends that the user develop the land pattern that will provide the best design for proper solder reflow and device attach for their specific application. Please review Custom MMIC Application Note AN 105 for a recommended land pattern approach.

#### Recommended Solder Reflow Profile


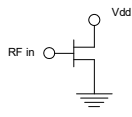
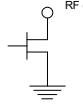
Custom MMIC recommends screen printing with belt furnace reflow to ensure proper solder reflow and device attach. Please review Custom MMIC Application Note AN 102 for a recommended solder reflow profile.

### Pin Description

#### Pin Diagram

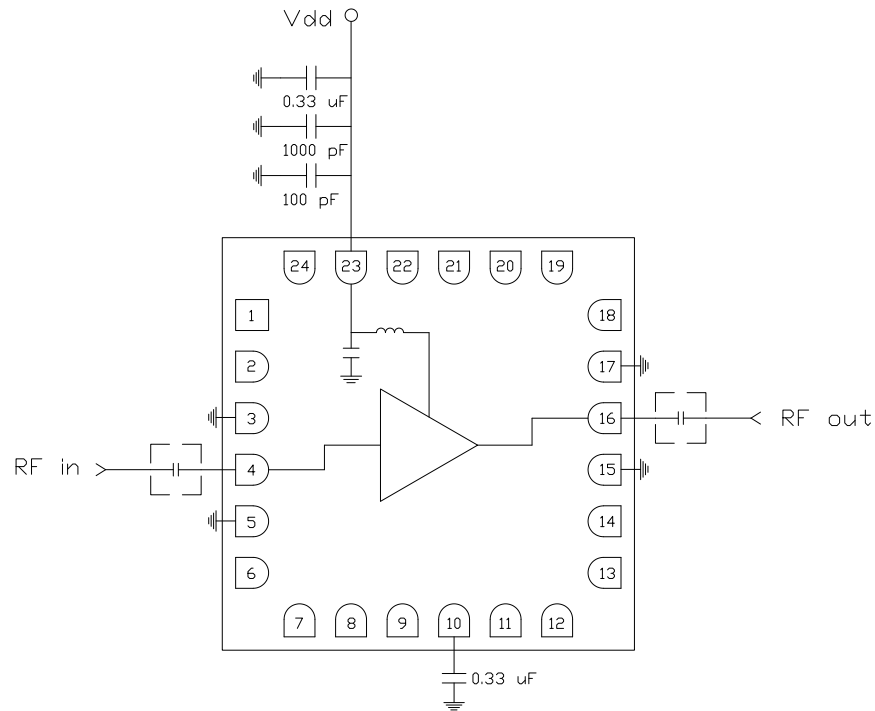


#### Functional Description

| Pad                         | Function | Description                                                                | Schematic                                                                             |
|-----------------------------|----------|----------------------------------------------------------------------------|---------------------------------------------------------------------------------------|
| 1, 2, 6-9, 11-14, 18-22, 24 | N/C      | No connection required. These pins may be connected to RF/DC ground.       |                                                                                       |
| 3, 5, 15, 17 and die paddle | Ground   | Connect to RF / DC ground                                                  |  |
| 4                           | RF in    | 50 ohm matched input<br>External DC block required                         |  |
| 23                          | Vdd      | Power supply voltage<br>Decoupling and bypass caps required                |                                                                                       |
| 16                          | RF out   | 50 ohm matched output<br>External DC block required                        |  |
| 10                          | ACG      | Low frequency termination. Attach bypass capacitor per application circuit |                                                                                       |

### Applications Information

#### Application Circuit



#### Biasing and Operation

The CMD317C4 is biased with a single positive drain supply. Performance is optimized when the drain voltage is set to +8.0 V.

Turn ON procedure:

1. Apply drain voltage  $V_{dd}$  and set to +8 V

Turn OFF procedure:

1. Turn off drain voltage  $V_{dd}$

RF power can be applied at any time.

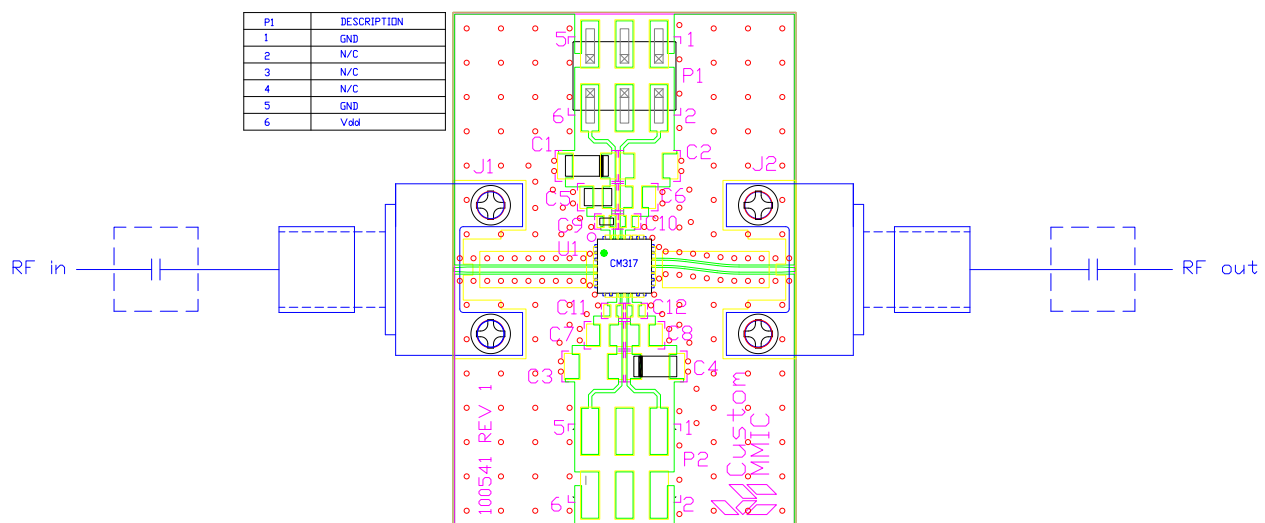
**GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.**

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### Applications Information

#### Evaluation Board

The circuit board shown has been developed for optimized assembly at Custom MMIC. A sufficient number of via holes should be used to connect the top and bottom ground planes. As surface mount processes vary, careful process development is recommended.



#### Bill of Material

| Designator | Value        | Description               |
|------------|--------------|---------------------------|
| J1, J2     |              | SMA End Launch Connector  |
| P1         |              | 6 Pin Header              |
| C1, C4     | 0.33 $\mu$ F | Capacitor, Tantalum       |
| C5         | 1000 pF      | Capacitor, 0603           |
| C9         | 100 pF       | Capacitor, 0402           |
| U1         |              | CMD317C4 Driver Amplifier |
| PCB        |              | 100541 Evaluation PCB     |

Please note, All information contained in this data sheet is subject to change without notice.

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